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INFORMATION DISCLOSURE omplete if Known **Application Number** 09/483,881 January 18, 2000 Filing Date Ahn, Kie **First Named Inventor** 2812 **Group Art Unit** Nguyen, Ha **Examiner Name** Attorney Docket No: 303.672US1 Sheet 1 of 1

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	Group Art Unit	2812
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MAY 1 6 2005 6	Group Art Unit	2812
E TO THE STATE OF	Examiner Name	Nguyen, Ha
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